

RELIABILITY REPORT
FOR
MAX707CPA+
(MAX705-MAX708/MAX813)
PLASTIC ENCAPSULATED DEVICES

December 1, 2008

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.
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Approved by
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Quality Assurance
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Conclusion

The MAX707CPA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX705-MAX708/MAX813L microprocessor (μ P) supervisory circuits reduce the complexity and number of components required to monitor power-supply and battery functions in μ P systems. These devices significantly improve system reliability and accuracy compared to separate ICs or discrete components. The MAX705/MAX706/MAX813L provide four functions: 1) A reset output during power-up, power-down, and brownout conditions.

- 2) An independent watchdog output that goes low if the watchdog input has not been toggled within 1.6 seconds.
- 3) A 1.25V threshold detector for power-fail warning, low-battery detection, or for monitoring a power supply other than +5V.
- 4) An active-low manual-reset input. The MAX707/MAX708 are the same as the MAX705/ MAX706, except an active-high reset is substituted for the watchdog timer. The MAX813L is the same as the MAX705, except RESET is provided instead of RESET-bar. Two supply-voltage monitor levels are available: The MAX705/MAX707/MAX813L generate a reset pulse when the supply voltage drops below 4.65V, while the MAX706/MAX708 generate a reset pulse below 4.40V. All four parts are available in 8-pin DIP, SO and μ MAX® packages.

II. Manufacturing Information

A. Description/Function:	Low-Cost, μ P Supervisory Circuits
B. Process:	S3
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Unisem Malaysia, Hana Thailand, ATP Philippines, UTL Thailand
F. Date of Initial Production:	Pre 1997

III. Packaging Information

A. Package Type:	8-pin PDIP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1701-0103
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	110°C/W
K. Single Layer Theta Jc:	40°C/W

IV. Die Information

A. Dimensions:	51 X 74 mils
B. Passivation:	$\text{Si}_3\text{N}_4/\text{SiO}_2$ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

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|-----------------------------------|---|
| A. Quality Assurance Contacts: | Ken Wendel (Director, Reliability Engineering)
Bryan Preeshl (Managing Director of QA) |
| B. Outgoing Inspection Level: | 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects. |
| C. Observed Outgoing Defect Rate: | < 50 ppm |
| D. Sampling Plan: | Mil-Std-105D |

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are pending. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 1160 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 0.93 \times 10^{-9}$$

$$\lambda = 0.93 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the S3 Process results in a FIT Rate of 3.6 @ 25C and 66.0 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The PW27-2 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1500 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX707CPA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	1160	0
Moisture Testing (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data